

# SOT1045-1

plastic dual in-line compatible thermal enhanced extremely thin quad flat package; no leads; 20 terminals; UTLP based

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	DHXQFN20U
<b>Package type industry code</b>	DHXQFN20U
<b>Package style descriptive code</b>	DHXQFN (DIL-compatible thermal enhanced extremely thin quad flatpack; no leads)
<b>Package style suffix code</b>	U (UTLP based)
<b>Package body material type</b>	P (plastic)
<b>IEC package outline code</b>	- - -
<b>JEITA package outline code</b>	- - -
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	4-8-2009

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	4.4	-	4.5	4.6	mm
E	package width	2.4	-	2.5	2.6	mm
A	seated height	[tbd]	-	0.5	0.5	mm
e	nominal pitch	-	-	0.5	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	20	-	

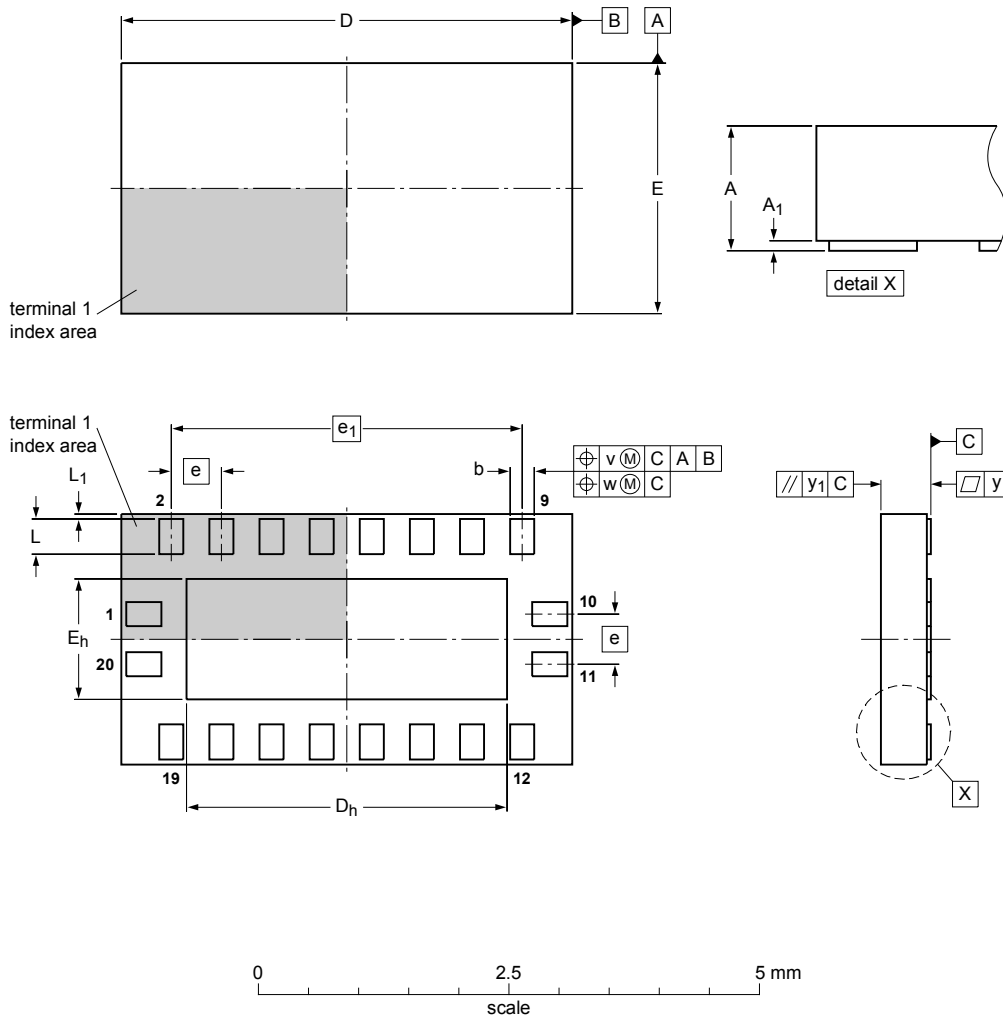


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## 2. Package outline

DHXQFN20U: plastic dual in-line compatible thermal enhanced extremely thin quad flat package; no leads; 20 terminals; UTLP based; body 2.5 x 4.5 x 0.5 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A max	A <sub>1</sub>	b	D	D <sub>h</sub>	E	E <sub>h</sub>	e	e <sub>1</sub>	L	L <sub>1</sub>	v	w	y	y <sub>1</sub>
mm	0.5	0.05 0.00	0.30 0.18	4.6 4.4	3.35 3.05	2.6 2.4	1.35 1.05	0.5	3.5	0.45 0.25	0.13 0.05	0.1	0.05	0.05	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT1045-1	---		---			07-12-01 09-08-04

Fig. 1. Package outline DHXQFN20U (SOT1045-1)

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### 3. Legal information

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